

ABSTRACT OF THE DISCLOSURE

A bonding apparatus is constituted by a bonding tool,  
a substrate stage, a moving mechanism for moving the bonding  
tool and the substrate stage, an up-and-down mechanism for  
5 moving up and down said bonding tool, and a chip recognition  
camera. The bonding apparatus is configured so that a chip  
and a substrate are subjected to positioning on the basis of  
a recognition result of the chip recognition camera so that  
the chip is bonded onto the substrate. The chip recognition  
10 camera is disposed to be lower than a level of a substrate  
mounted surface of the substrate stage. A lower surface of  
the chip is recognized in a condition that the lower surface  
of the chip is located to be substantially on a level with  
a chip bonding surface of the substrate. Positioning of the  
15 chip and the substrate is performed by the recognition image.